

A SEMICONDUCTOR PACKAGE AND METHOD FOR FORMING SAME

Abstract of the Invention

5 A chip scale semiconductor package (2) with an inverted die
(5) having pads (6) directly bonded by thermocompression tin-gold
bonding to bond locations (10) on runners (12) of a flexible substrate
(9). Solder balls (20) are attached to the runners (12) through holes
(15) in the flexible substrate (9) to form a ball grid array for
10 mounting the package (2) on a printed circuit board.

(FIG. 1 accompanies this abstract)

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